

# 74ABT374A

Octal D-type flip-flop; positive-edge trigger; 3-state

Rev. 2 — 18 December 2012

Product data sheet

## 1. General description

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The 74ABT374A high-performance BiCMOS device combines low static and dynamic power dissipation with high speed and high output drive.

The 74ABT374A is an 8-bit, edge triggered register coupled to eight 3-state output buffers. The two sections of the device are controlled independently by the clock input (CP) and output enable input ( $\overline{OE}$ ) control gates.

The register is fully edge-triggered. The state of each D input, one set-up time before the LOW-to-HIGH clock transition, is transferred to the corresponding flip-flop's Q output.

The 3-state output buffers are designed to drive heavily loaded 3-state buses, MOS memories, or MOS microprocessors. The active LOW output enable ( $\overline{OE}$ ) controls all eight 3-state buffers independent of the clock operation.

When  $\overline{OE}$  is LOW, the stored data appears at the outputs. When  $\overline{OE}$  is HIGH, the outputs are in the high-impedance "OFF" state, which means they will neither drive nor load the bus.

## 2. Features and benefits

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- 8-bit positive edge triggered register
- 3-state output buffers
- Power-on 3-state
- Power-on reset
- Output capability: +64 mA/–32 mA
- Latch-up protection exceeds 500 mA per JESD78B class II level A
- ESD protection:
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V
- Live insertion/extraction permitted

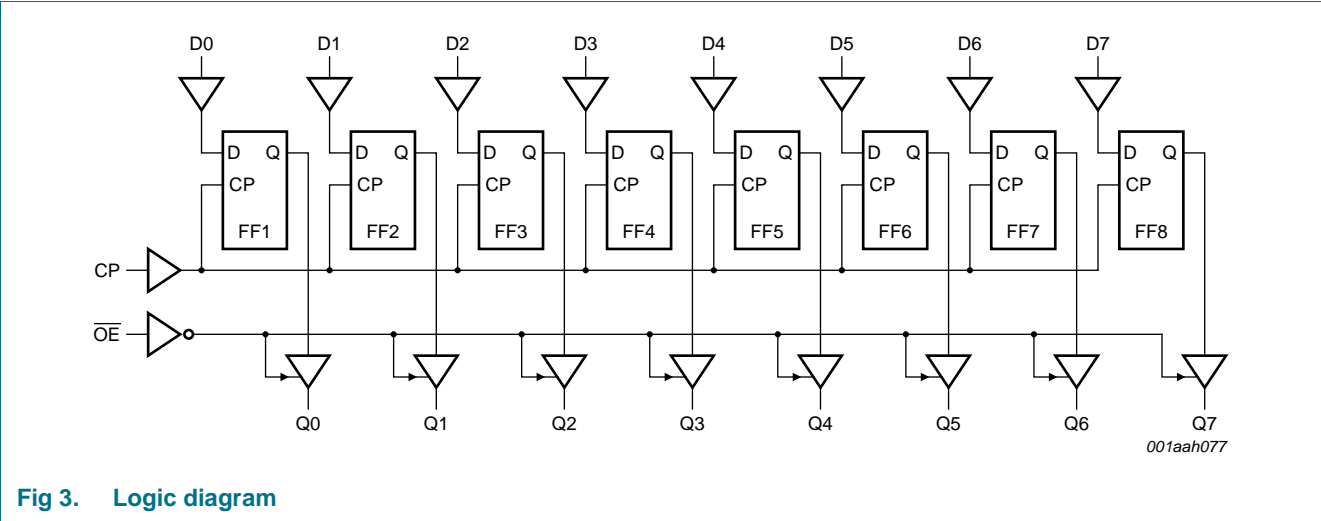
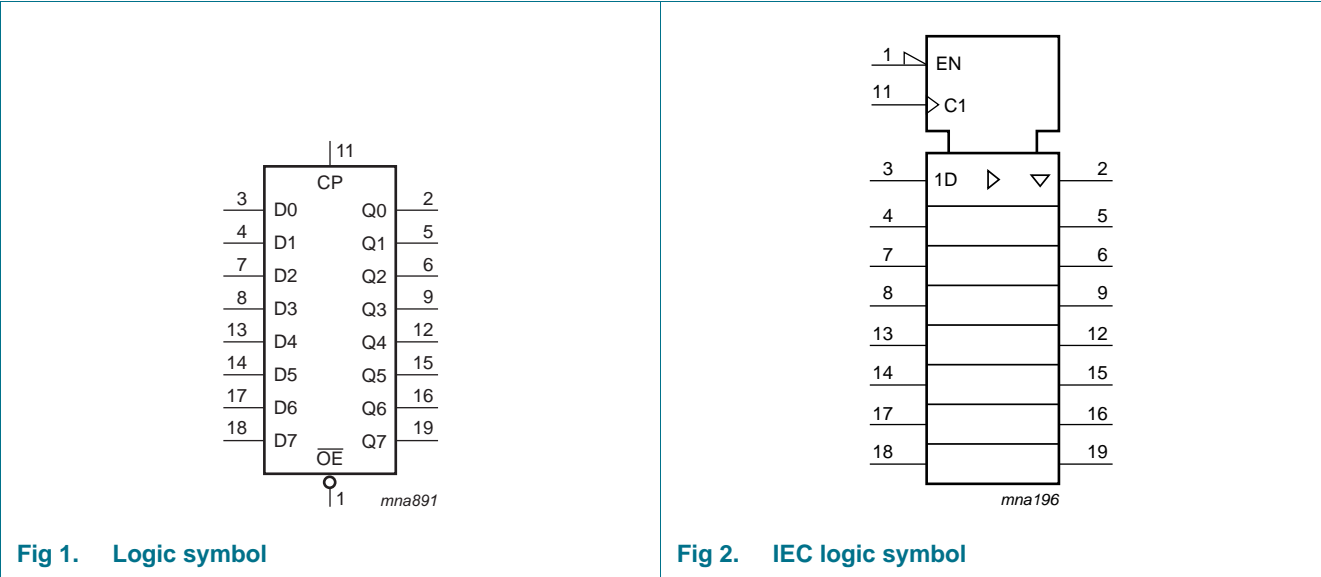


3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74ABT374AN	−40 °C to +85 °C	DIP20	plastic dual in-line package; 20 leads (300 mil)	SOT146-1
74ABT374AD	−40 °C to +85 °C	SO20	plastic small outline package; 20 leads; body width 7.5 mm	SOT163-1
74ABT374ADB	−40 °C to +85 °C	SSOP20	plastic shrink small outline package; 20 leads; body width 5.3 mm	SOT339-1
74ABT374APW	−40 °C to +85 °C	TSSOP20	plastic thin shrink small outline package; 20 leads; body width 4.4 mm	SOT360-1

4. Functional diagram



## 5. Pinning information

### 5.1 Pinning

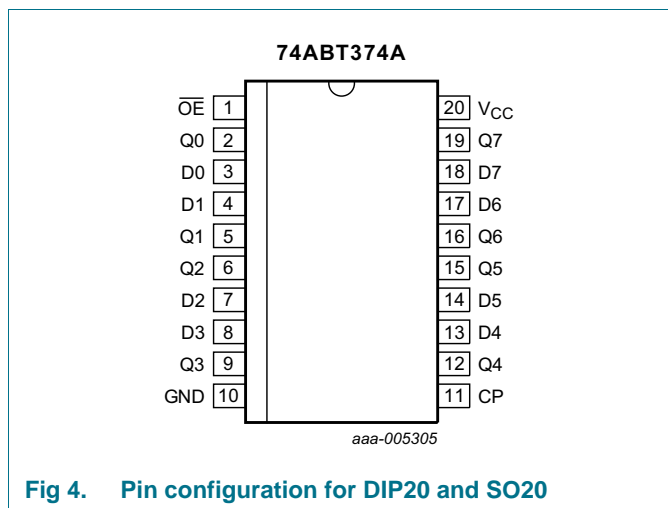


Fig 4. Pin configuration for DIP20 and SO20

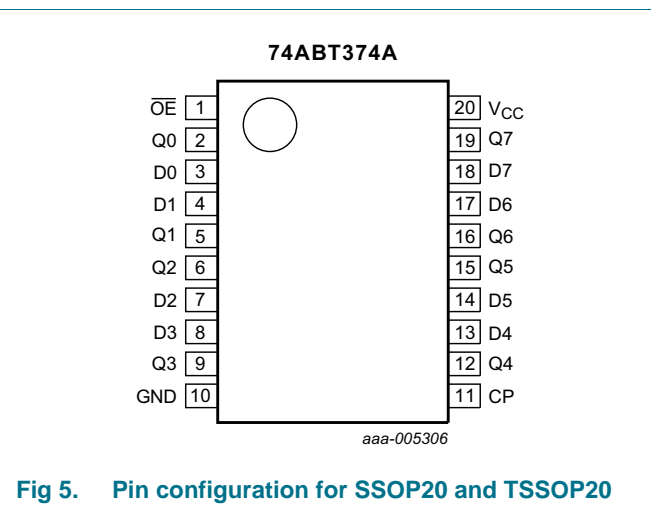


Fig 5. Pin configuration for SSOP20 and TSSOP20

### 5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
OE	1	3-state output enable input (active LOW)
D0, D1, D2, D3, D4, D5, D6, D7	3, 4, 7, 8, 13, 14, 17, 18	data input
GND	10	ground (0 V)
CP	11	clock pulse input (active rising edge)
Q0, Q1, Q2, Q3, Q4, Q5, Q6, Q7	2, 5, 6, 9, 12, 15, 16, 19	3-state flip-flop output
V <sub>CC</sub>	20	supply voltage

## 6. Functional description

Table 3. Function table<sup>[1]</sup>

Operating mode	Input			Internal flip-flop	Output Qn
	OE	CP	Dn		
Load and read register	L	↑	l	L	L
	L	↑	h	H	H
Load register and disable output	H	↑	l	L	Z
	H	↑	h	H	Z

- [1] H = HIGH voltage level  
 h = HIGH voltage level one setup time prior to the LOW-to-HIGH CP transition  
 L = LOW voltage level  
 l = LOW voltage level one setup time prior to the LOW-to-HIGH CP transition  
 Z = high-impedance OFF-state  
 ↑ = LOW-to-HIGH clock transition

## 7. Limiting values

**Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		-0.5	+7.0	V
$V_I$	input voltage		[1] -1.2	+7.0	V
$V_O$	output voltage	output in OFF-state or HIGH-state	[1] -0.5	+5.5	V
$I_{IK}$	input clamping current	$V_I < 0$ V	-18	-	mA
$I_{OK}$	output clamping current	$V_O < 0$ V	-50	-	mA
$I_O$	output current	output in LOW-state	-	128	mA
$T_j$	junction temperature		[2] -	150	°C
$T_{stg}$	storage temperature		-65	+150	°C

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150 °C.

## 8. Recommended operating conditions

**Table 5. Operating conditions**

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC}$	supply voltage		4.5	-	5.5	V
$V_I$	input voltage		0	-	$V_{CC}$	V
$V_{IH}$	HIGH-level input voltage		2.0	-	-	V
$V_{IL}$	LOW-level input voltage		-	-	0.8	V
$I_{OH}$	HIGH-level output current		-32	-	-	mA
$I_{OL}$	LOW-level output current		-	-	64	mA
$\Delta t/\Delta V$	input transition rise and fall rate		0	-	10	ns/V
$T_{amb}$	ambient temperature	in free air	-40	-	+85	°C

## 9. Static characteristics

**Table 6. Static characteristics**

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		Unit
			Min	Typ	Max	Min	Max	
$V_{IK}$	input clamping voltage	$V_{CC} = 4.5$ V; $I_{IK} = -18$ mA	-1.2	-0.9	-	-1.2	-	V
$V_{OH}$	HIGH-level output voltage	$V_I = V_{IL}$ or $V_{IH}$						
		$V_{CC} = 4.5$ V; $I_{OH} = -3$ mA	2.5	2.9	-	2.5	-	V
		$V_{CC} = 5.0$ V; $I_{OH} = -3$ mA	3.0	3.4	-	3.0	-	V
		$V_{CC} = 4.5$ V; $I_{OH} = -32$ mA	2.0	2.4	-	2.0	-	V
$V_{OL}$	LOW-level output voltage	$V_{CC} = 4.5$ V; $I_{OL} = 64$ mA; $V_I = V_{IL}$ or $V_{IH}$	-	0.42	0.55	-	0.55	V

Table 6. Static characteristics ...continued

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		Unit
			Min	Typ	Max	Min	Max	
$V_{OL(pu)}$	power-up LOW-level output voltage	$V_{CC} = 5.5 \text{ V}$ ; $I_O = 1 \text{ mA}$ ; $V_I = \text{GND or } V_{CC}$ [1]	-	0.13	0.55	-	0.55	V
$I_I$	input leakage current	$V_{CC} = 5.5 \text{ V}$ ; $V_I = V_{CC} \text{ or } \text{GND}$	-	$\pm 0.01$	$\pm 1.0$	-	$\pm 1.0$	$\mu\text{A}$
$I_{OFF}$	power-off leakage current	$V_{CC} = 0 \text{ V}$ ; $V_I \text{ or } V_O \leq 4.5 \text{ V}$	-	$\pm 5.0$	$\pm 100$	-	$\pm 100$	$\mu\text{A}$
$I_{O(pu/pd)}$	power-up/power-down output current	$V_{CC} = 2.0 \text{ V}$ ; $V_O = 0.5 \text{ V}$ ; $V_I = \text{GND or } V_{CC}$ ; OE HIGH [2]	-	$\pm 5.0$	$\pm 50$	-	$\pm 50$	$\mu\text{A}$
$I_{OZ}$	OFF-state output current	$V_{CC} = 5.5 \text{ V}$ ; $V_I = V_{IL} \text{ or } V_{IH}$						
		$V_O = 2.7 \text{ V}$	-	5.0	50	-	50	$\mu\text{A}$
		$V_O = 0.5 \text{ V}$	-50	-5.0	-	-50	-	$\mu\text{A}$
$I_{LO}$	output leakage current	HIGH-state; $V_O = 5.5 \text{ V}$ ; $V_{CC} = 5.5 \text{ V}$ ; $V_I = \text{GND or } V_{CC}$	-	5.0	50	-	50	$\mu\text{A}$
$I_O$	output current	$V_{CC} = 5.5 \text{ V}$ ; $V_O = 2.5 \text{ V}$ [3]	-180	-100	-50	-180	-50	mA
$I_{CC}$	supply current	$V_{CC} = 5.5 \text{ V}$ ; $V_I = \text{GND or } V_{CC}$						
		outputs HIGH-state	-	110	250	-	250	$\mu\text{A}$
		outputs LOW-state	-	24	30	-	30	mA
		outputs disabled	-	110	250	-	250	$\mu\text{A}$
$\Delta I_{CC}$	additional supply current	per input pin; $V_{CC} = 5.5 \text{ V}$ ; one input at 3.4 V; other inputs at $V_{CC} \text{ or } \text{GND}$ [4]	-	0.5	1.5	-	1.5	mA
$C_I$	input capacitance	$V_I = 0 \text{ V or } V_{CC}$	-	4	-	-	-	pF
$C_O$	output capacitance	outputs disabled; $V_O = 0 \text{ V or } V_{CC}$	-	7	-	-	-	pF

[1] For valid test results, data must not be loaded into the flip-flops (or latches) after applying the power.

[2] This parameter is valid for any  $V_{CC}$  between 0 V and 2.1 V, with a transition time of up to 10 ms. From  $V_{CC} = 2.1 \text{ V}$  to  $V_{CC} = 5 \text{ V} \pm 10 \%$  a transition time of up to 100  $\mu\text{s}$  is permitted.

[3] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[4] This is the increase in supply current for each input at 3.4 V.

## 10. Dynamic characteristics

Table 7. Dynamic characteristics

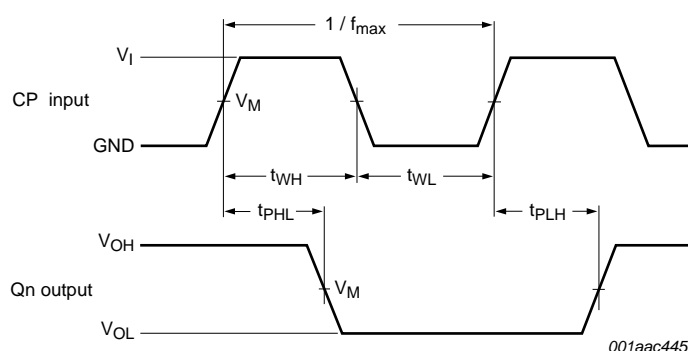
$\text{GND} = 0 \text{ V}$ ; for test circuit, see Figure 9.

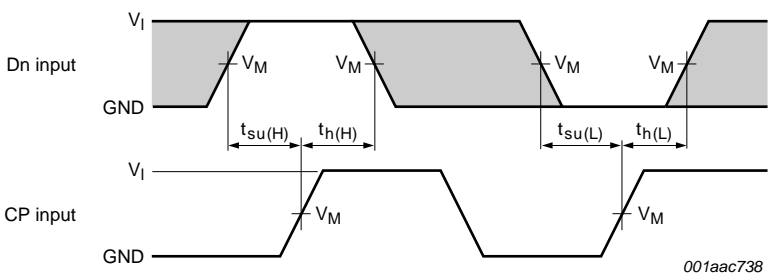
Symbol	Parameter	Conditions	25 °C; $V_{CC} = 5.0 \text{ V}$			–40 °C to +85 °C; $V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V}$		Unit
			Min	Typ	Max	Min	Max	
$f_{\max}$	maximum frequency	see Figure 6	200	300	-	200	-	MHz
$t_{PLH}$	LOW to HIGH propagation delay	CP to Qn; see Figure 6	1.7	3.4	4.5	1.7	5.1	ns
$t_{PHL}$	HIGH to LOW propagation delay	CP to Qn; see Figure 6	2.0	3.8	4.9	2.0	5.2	ns
$t_{PZH}$	OFF-state to HIGH propagation delay	$\overline{\text{OE}}$ to Qn; see Figure 8	1.2	3.5	4.5	1.2	5.4	ns

**Table 7. Dynamic characteristics ...continued**GND = 0 V; for test circuit, see [Figure 9](#).

Symbol	Parameter	Conditions	25 °C; V <sub>CC</sub> = 5.0 V			–40 °C to +85 °C; V <sub>CC</sub> = 5.0 V ± 0.5 V		Unit
			Min	Typ	Max	Min	Max	
t <sub>PZL</sub>	OFF-state to LOW propagation delay	$\overline{OE}$ to Qn; see <a href="#">Figure 8</a>	2.2	4.3	5.4	2.2	6.2	ns
t <sub>PHZ</sub>	HIGH to OFF-state propagation delay	$\overline{OE}$ to Qn; see <a href="#">Figure 8</a>	1.8	3.6	4.7	1.8	5.2	ns
t <sub>PLZ</sub>	LOW to OFF-state propagation delay	$\overline{OE}$ to Qn; see <a href="#">Figure 8</a>	1.5	3.0	4.1	1.5	4.3	ns
t <sub>su(H)</sub>	set-up time HIGH	Dn to CP; see <a href="#">Figure 7</a>	1.5	0.6	-	1.5	-	ns
t <sub>su(L)</sub>	set-up time LOW	Dn to CP; see <a href="#">Figure 7</a>	1.2	0.3	-	1.2	-	ns
t <sub>h(H)</sub>	hold time HIGH	CP to Dn; see <a href="#">Figure 7</a>	1.0	–0.3	-	1.0	-	ns
t <sub>h(L)</sub>	hold time LOW	CP to Dn; see <a href="#">Figure 7</a>	1.0	–0.5	-	1.0	-	ns
t <sub>WH</sub>	pulse width HIGH	CP; see <a href="#">Figure 6</a>	2.0	0.8	-	2.0	-	ns
t <sub>WL</sub>	pulse width LOW	CP; see <a href="#">Figure 6</a>	2.8	1.0	-	2.8	-	ns

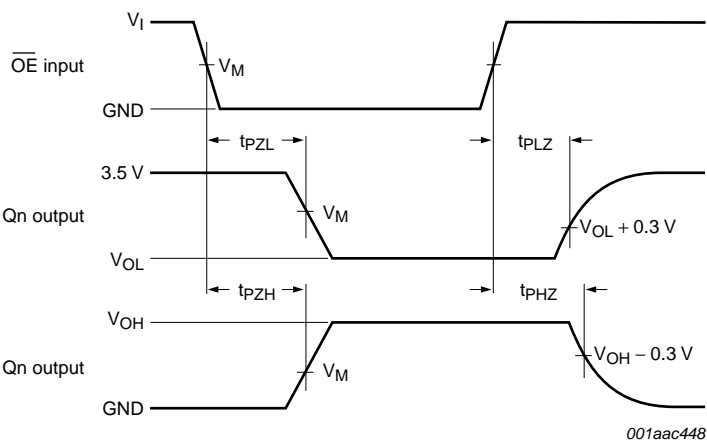
## 11. Waveforms

 $V_M = 1.5\text{ V}$  $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.**Fig 6. Propagation delay clock input (CP) to output (Qn), clock pulse (CP) width and maximum clock (CP) frequency**



$V_M = 1.5\text{ V}$   
The shaded areas indicate when the input is permitted to change for predictable output performance.

**Fig 7. Set-up and hold times data output (Dn) to clock (CP)**



$V_M = 1.5\text{ V}$   
 $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load

**Fig 8. 3-state output (Qn) enable and disable times**

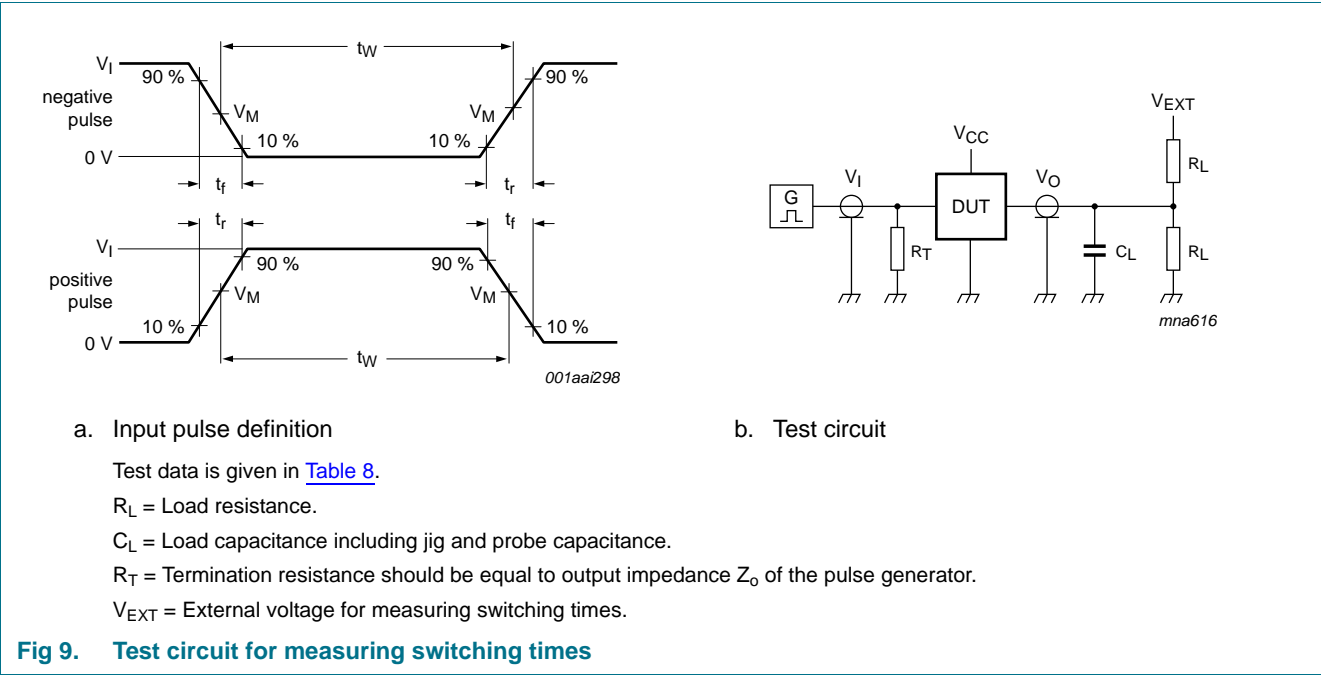


Table 8. Test data

Input				Load		$V_{EXT}$		
$V_I$	$f_i$	$t_W$	$t_r, t_f$	$C_L$	$R_L$	$t_{PHL}, t_{PLH}$	$t_{PZH}, t_{PHZ}$	$t_{PZL}, t_{PLZ}$
3.0 V	1 MHz	500 ns	$\leq 2.5$ ns	50 pF	500 $\Omega$	open	open	7.0 V



12. Package outline

DIP20: plastic dual in-line package; 20 leads (300 mil) SOT146-1

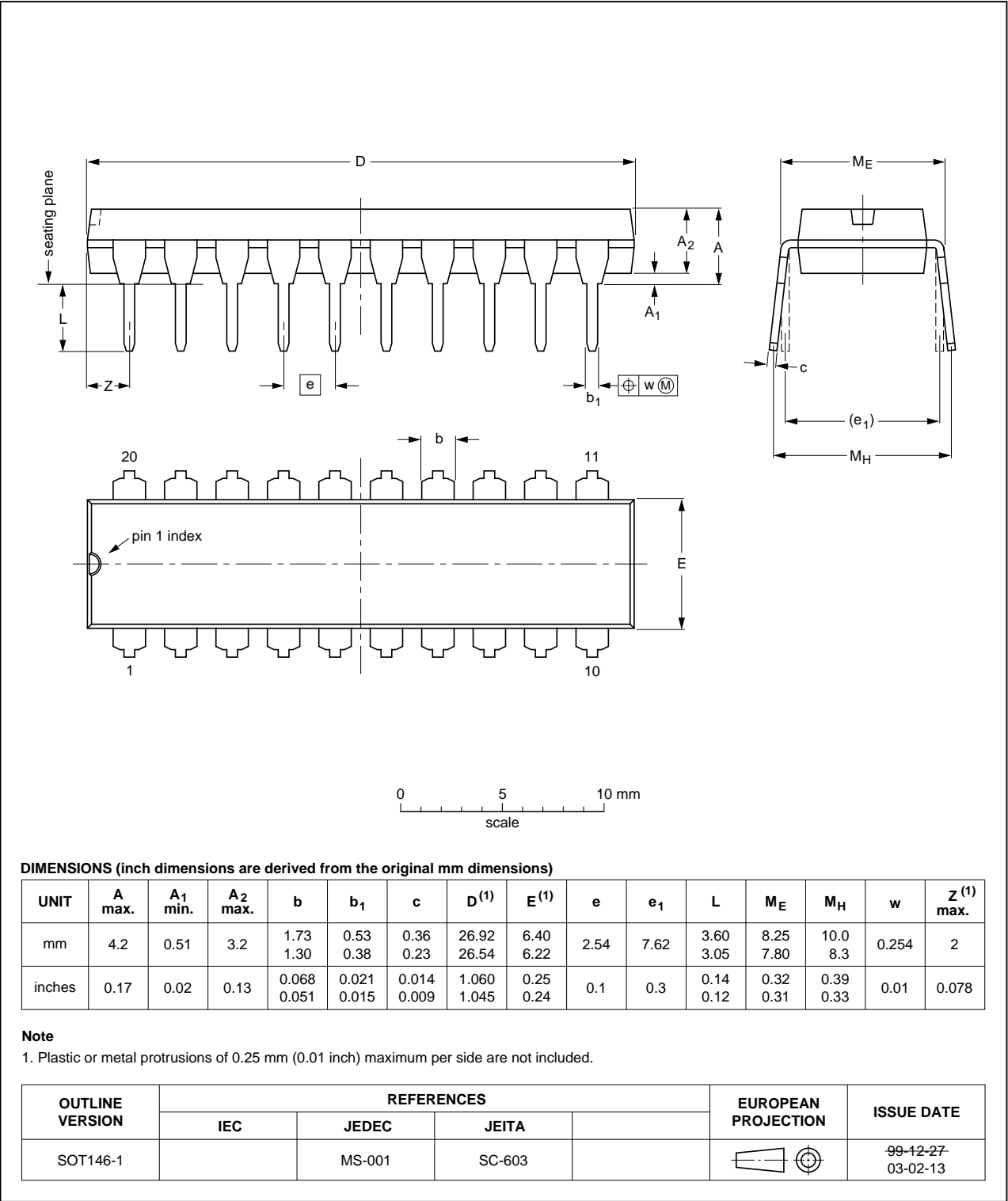
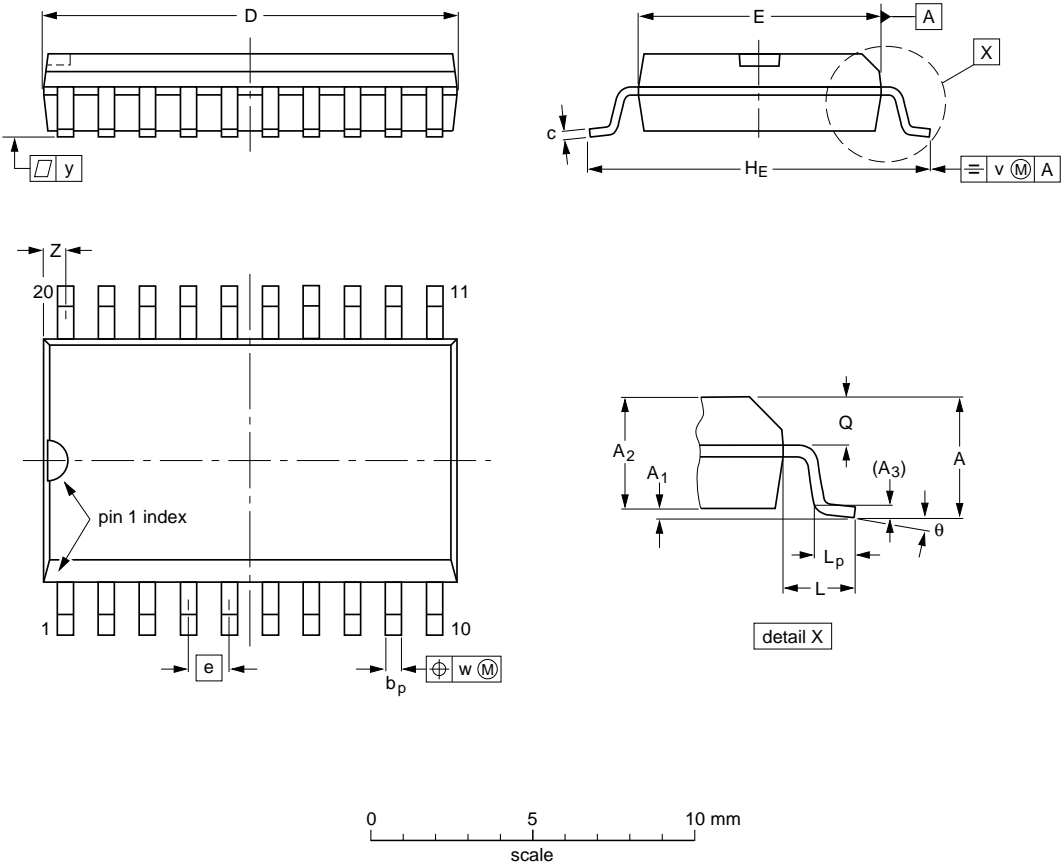


Fig 10. Package outline SOT146-1 (DIP20)

SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	2.65	0.3 0.1	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8° 0°
inches	0.1	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.05	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

**Note**  
1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT163-1	075E04	MS-013				99-12-27 03-02-19

Fig 11. Package outline SOT163-1 (SO20)

SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm

SOT339-1

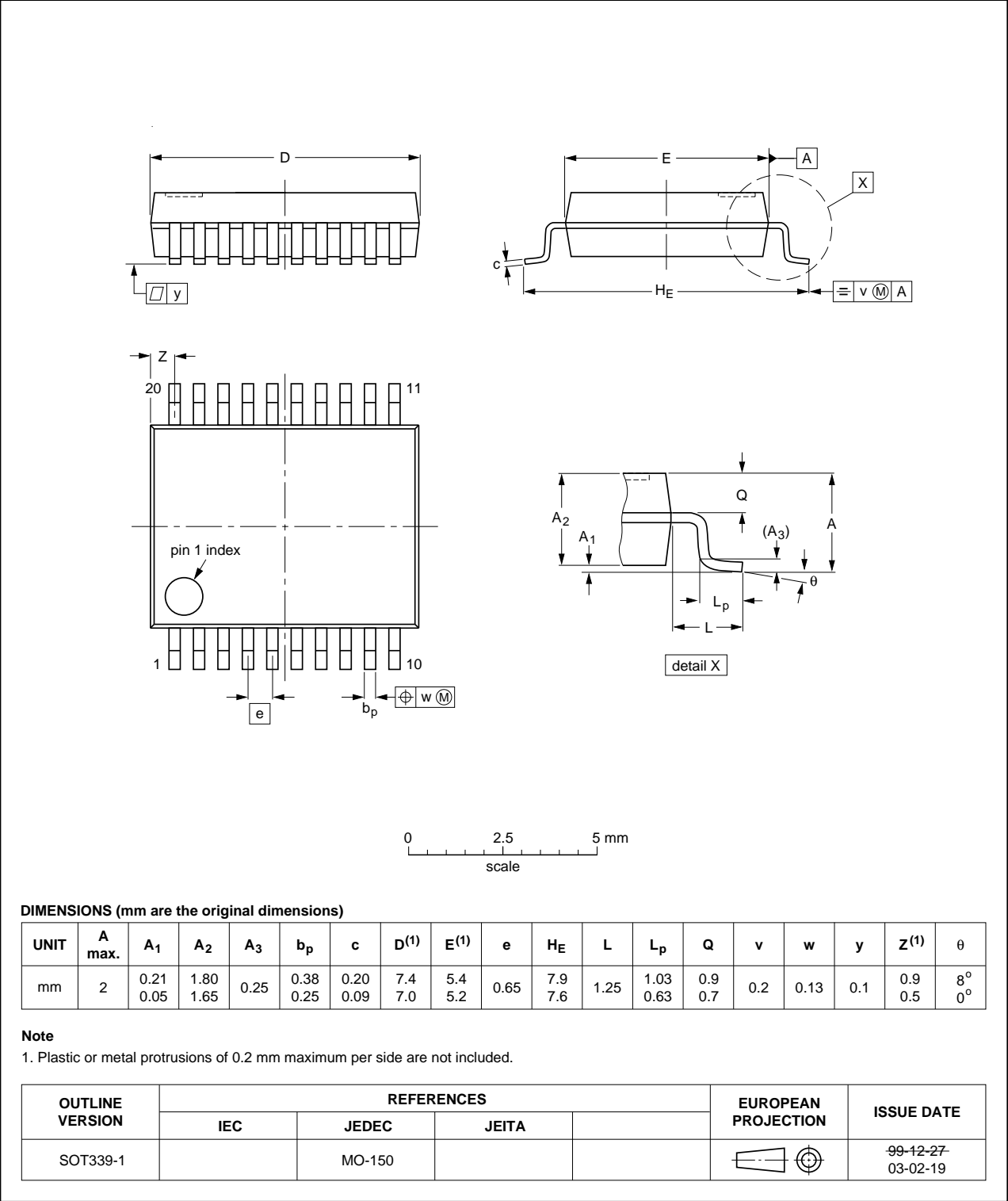


Fig 12. Package outline SOT339-1 (SSOP20)

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1

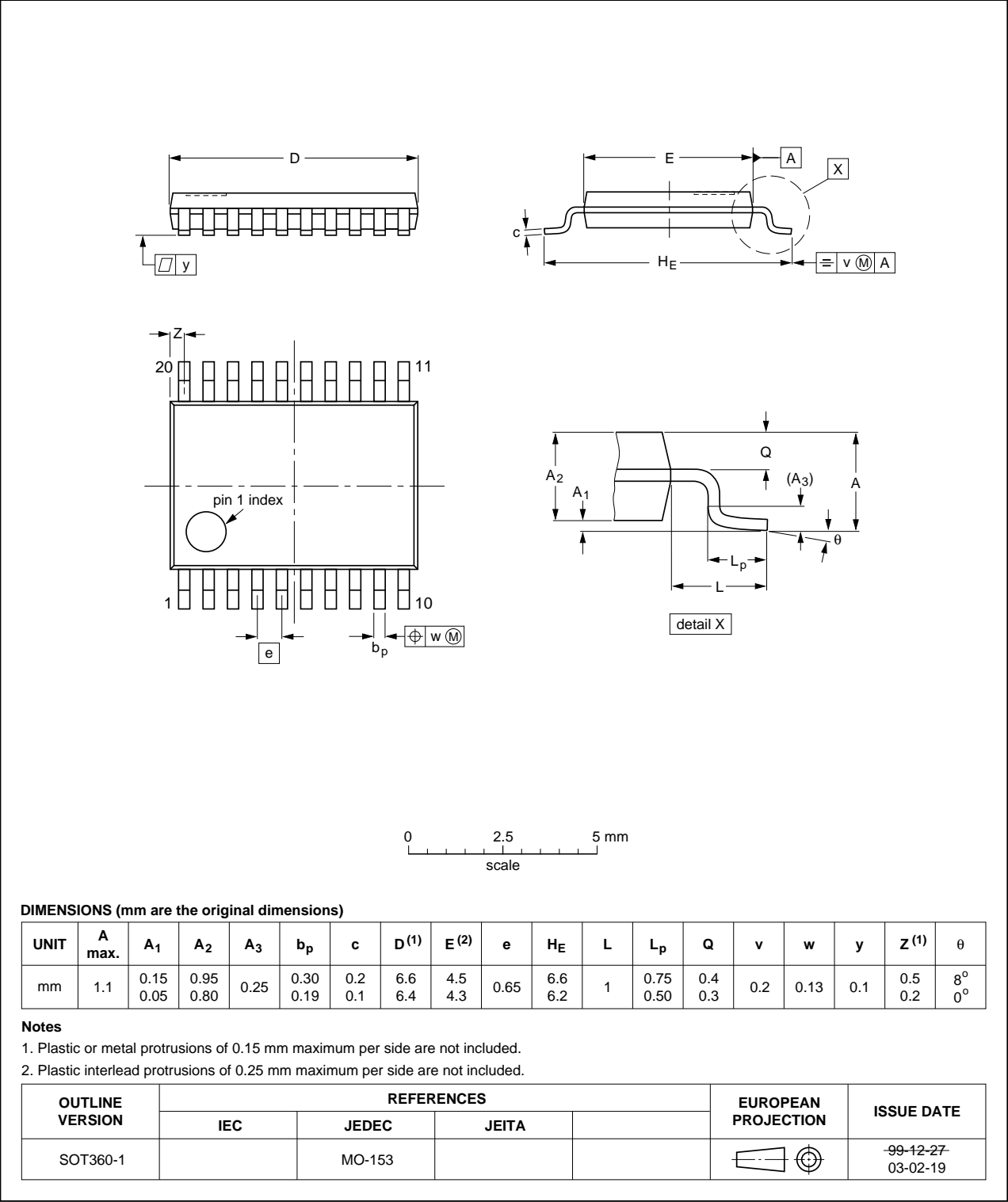


Fig 13. Package outline SOT360-1 (TSSOP20)

## 13. Abbreviations

Table 9. Abbreviations

Acronym	Description
BiCMOS	Bipolar Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model

## 14. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74ABT374A v.2	20121218	Product data sheet	-	74ABT374A v.1
Modifications:	<ul style="list-style-type: none"><li>The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li><li>Legal texts have been adapted to the new company name where appropriate.</li></ul>			
74ABT374A v.1	19950906	Product specification	-	-

## 15. Legal information

### 15.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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